XP04212

Silicon NPN epitaxial planar type

For digital circuits

Features

- Two elements incorporated into one package (Transistors with built-in resistor)
- Reduction of the mounting area and assembly cost by one half

Basic Part Number

• UNR2212 \times 2

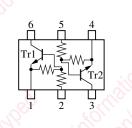
Absolute Maximum Ratings $T_a = 25^{\circ}C$

Symbol	Rating	Unit	
V _{CBO}	50	V	
V _{CEO}	50	V	
I _C	100	mA	
P _T	150	mW	
Tj	150	°C	
T _{stg}	-55 to +150	°C	
	V _{CBO} V _{CEO} I _C P _T T _j	$\begin{array}{c c} V_{CBO} & 50 \\ \hline V_{CEO} & 50 \\ \hline V_{CEO} & 50 \\ \hline I_C & 100 \\ \hline P_T & 150 \\ \hline T_j & 150 \\ \hline \end{array}$	

Package

- Code
- SMini6-G1 • Pin Name
 - 1: Emitter (Tr1)
 - r1) 4: Emitter (Tr2)
 - 2: Base (Tr1) 5: Base (Tr2)
 - 3: Collector (Tr2) 6
- $2) \quad 6: \text{Collector} (\text{Tr1})$
- Marking Symbol: 8R

Internal Connection



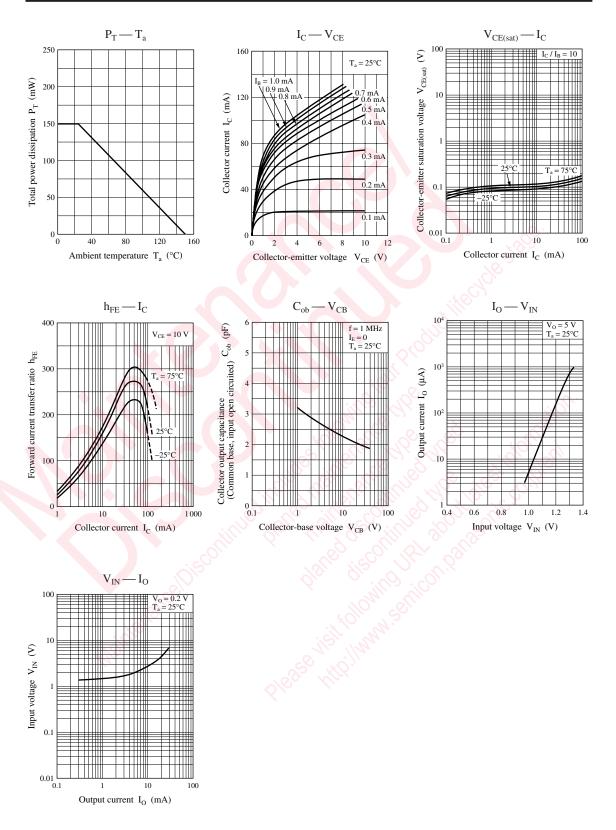
Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V _{CBO}	$I_{\rm C} = 10 \ \mu A, I_{\rm E} = 0$	50			V
Collector-emitter voltage (Base open)	V _{CEO}	$I_{\rm C} = 2 \text{ mA}, I_{\rm B} = 0$	50			V
Collector-base cutoff current (Emitter open)	I _{CBO}	$V_{CB} = 50 \text{ V}, I_E = 0$			0.1	μΑ
Collector-emitter cutoff current (Base open)	I _{CEO}	$V_{CE} = 50 \text{ V}, I_B = 0$			0.5	μΑ
Emitter-base cutoff current (Collector open)	I _{EBO}	$V_{EB} = 6 V, I_C = 0$			0.2	mA
Forward current transfer ratio	h _{FE}	$V_{CE} = 10 \text{ V}, I_{C} = 5 \text{ mA}$	60			
Collector-emitter saturation voltage	V _{CE(sat)}	$I_{\rm C} = 10 \text{ mA}, I_{\rm B} = 0.3 \text{ mA}$			0.25	V
Output voltage high-level	V _{OH}	$V_{CC} = 5 \text{ V}, \text{ V}_{B} = 0.5 \text{ V}, \text{ R}_{L} = 1 \text{ k}\Omega$	4.9			V
Output voltage low-level	V _{OL}	$V_{CC} = 5 \text{ V}, \text{V}_{B} = 2.5 \text{V}, \text{R}_{L} = 1 \text{k}\Omega$			0.2	V
Input resistance	R ₁		-30%	22	+30%	kΩ
Resistance ratio	R ₁ / R ₂		0.8	1.0	1.2	_
Transition frequency	f _T	$V_{CB} = 10 \text{ V}, I_E = -2 \text{ mA}, f = 200 \text{ MHz}$		150		MHz

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

XP04212

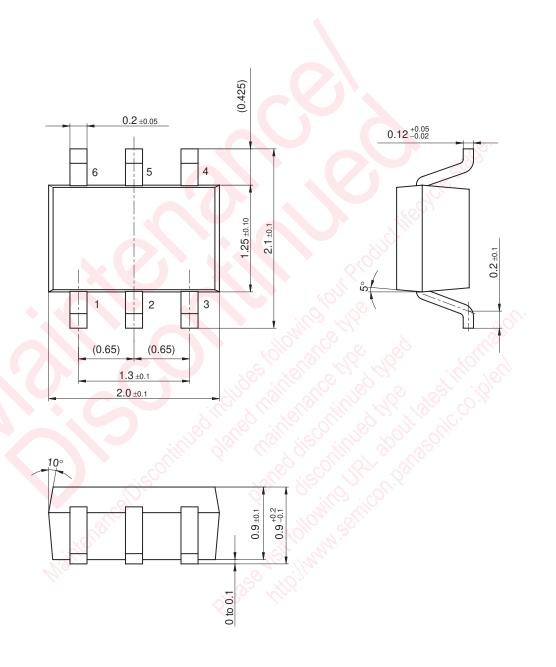




Panasonic

SMini6-G1

Unit: mm



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